

# 64K (8K×8) NMOS UV ERASABLE PROM

#### ■ FAST ACCESS TIME:

180ns MAX M2764A-1F1/M2764A-18F1

200ns MAX M2764A-2F1/M2764A-20F1

250ns MAX M2764AF1/M2764AF6/M2764A-25F1

300ns MAX M2764A-3F1/M2764A-30F1

450ns MAX M2764A-4F1/M2764A-4F6/M2764A-45F1

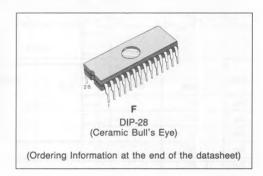
- 0 to +70°C STANDARD TEMPERATURE RANGE
- -40 to +85°C EXTENDED TEMPERATURE RANGE
- SINGLE +5V POWER SUPPLY
- ±10% V<sub>CC</sub> TOLERANCE AVAILABLE
- LOW STANDBY CURRENT (35mA MAX)
- TTL COMPATIBLE DURING READ AND PROGRAM
- FAST PROGRAMMING ALGORITHM
- ELECTRONIC SIGNATURE

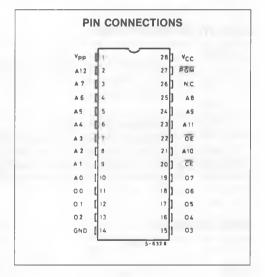
#### DESCRIPTION

The M2764A is a 65,536-bit ultraviolet erasable and electrically programmable read only memory (EPROM). It is organized as 8,192 words by 8 bits and manufactured using SGS-THOMSON' NMOS-E3 process.

The M2764A with its single +5V power supply and with an access time of 200ns, is ideal for use with high performance +5V microprocessor such as Z8, Z80 and Z8000. The M2764A has an important feature which is to separate the output control, Ouptut Enable (OE) from the Chip Enable control (CE). The OE control eliminates bus contention in multiple bus microprocessor systems.

The M2764A also features a standby mode which reduces the power dissipation without increasing access time. The active current is 75mA while the maximum standby current is only 35 mA, a 53% saving. The standby mode is achieved by applying a TTL-high signal to the CE input. The M2764A has an "Electronic Signature" that allows programmers to automatically identify device type and pinout. The M2764A is available in a 28-lead dual in-line ceramic package (frit-seal) glass lens.

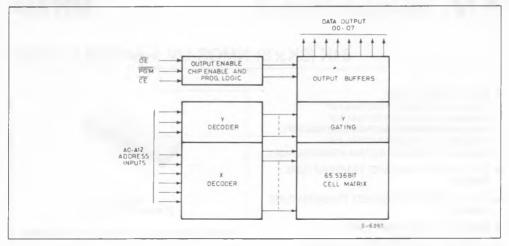




#### **PIN NAMES**

A0-A12	ADDRESS INPUT
CE	CHIP ENABLE INPUT
ŌĒ	OUTPUT ENABLE INPUT
PGM	PROGRAM
N.C.	NO CONNECTION
00-07	DATA INPUT/OUTPUT

### **BLOCK DIAGRAM**



### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Values	Unit
VI	All Input or Output voltages with respect to ground	+6.5 to -0.6	V
V <sub>PP</sub>	Supply voltage with respect to ground	+14 to -0,6	V
Tamb	Ambient temperature under bias /F1 /F6	- 10 to +80 - 50 to +95	°C
T <sub>stg</sub>	Storage temperature range	- 65 to +125	°C
	Voltage on pin 24 with respect to ground	+13.5 to -0.6	٧

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **OPERATING MODES**

MODE	CE (20)	OE (22)	A9 (24)	PGM (27)	V <sub>pp</sub> (1)	V <sub>CC</sub> (28)	OUTPUTS (11-13, 15-19)
READ	V <sub>IL</sub>	V <sub>IL</sub>	х	VIH	V <sub>CC</sub>	Vcc	D <sub>OUT</sub>
OUTPUT DISABLE	VIL	V <sub>IH</sub>	Х	V <sub>IH</sub>	V <sub>CC</sub>	Vcc	HIGH Z
STANDBY	V <sub>IH</sub>	Х	Х	Х	V <sub>CC</sub>	Vcc	HIGH Z
FAST PROGRAMMING	V <sub>IL</sub>	VIH	Х	VIL	V <sub>PP</sub>	Vcc	D <sub>IN</sub>
VERIFY	V <sub>IL</sub>	VIL	Х	V <sub>IH</sub>	V <sub>PP</sub>	Vcc	D <sub>OUT</sub>
PROGRAM INHIBIT	V <sub>IH</sub>	Х	х	Х	V <sub>PP</sub>	Vcc	HIGH Z
ELECTRONIC SIGNATURE	V <sub>IL</sub>	V <sub>IL</sub>	VH	V <sub>IH</sub>	V <sub>CC</sub>	V <sub>CC</sub>	CODES

NOTE: X can be  $V_{IH}$  or  $V_{IL}$   $V_H = 12V \pm 0.5V$ 

#### READ OPERATION

### DC AND AC CONDITIONS

Selection Code	F1/-1F1/-2F1 -3F1/-4F1	- <b>18F1</b> / - <b>20F1</b> / - <b>25F1</b> - 30F1/ - 45F1	F6/ - 4F6
Operating Temperature Range	0 to 70°C	0 to 70°C	- 40 to 85°C
V <sub>CC</sub> Power Supply (1,2)	5V ±5%	5V ±10%	5V ±5%
V <sub>PP</sub> Voltage (2)	$V_{PP} = V_{CC}$	V <sub>PP</sub> = V <sub>CC</sub>	V <sub>PP</sub> = V <sub>CC</sub>

# DC AND OPERATING CHARACTERISTICS

0				Values		
Symbol	Parameter	Test Conditions	Min.	Тур.(3)	Max.	Unit
ILI	Input Load Current	V <sub>IN</sub> = 5.5V			10	μА
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 5.5V			10	μА
IPP1(2)	V <sub>PP</sub> Current Read	Vpp = 5.5V			5	mA
I <sub>CC1(2)</sub>	V <sub>CC</sub> Current Standby	CE = VIH			35	mA
I <sub>CC2(2)</sub>	V <sub>CC</sub> Current Active	CE = OE = VIL			75	mA
V <sub>IL</sub>	Input Low Voltage		-0.1		+0.8	V
V <sub>IH</sub>	Input High Voltage		2.0		V <sub>CC</sub> +1	V
VOL	Output Low Voltage	I <sub>OL</sub> = 2.1 mA			0.45	V
V <sub>OH</sub>	Output High Voltage	$I_{OH} = -400 \ \mu A$	2.4			V
V <sub>PP(2)</sub>	V <sub>PP</sub> Read Voltage	$V_{CC} = 5V \pm 0.25V$	3.8		V <sub>CC</sub>	V

### AC CHARACTERISTICS

		V <sub>CC</sub> ± 5%	276	4A-1	276	4A-2	276	64A	276	4A-3	276	4A-4	
Symbol	Parameter	V <sub>CC</sub> ± 10%	2764	A-18	2764	A-20	2764	A-25	2764	A-30	2764	A-45	Unit
		Test Conditions	Min	Max									
tACC	Address to Output Delay	CE = OE = VIL		180		200		250		300		450	ns
t <sub>CE</sub>	CE to Output Delay	OE = V <sub>IL</sub>		180		200		250		300		450	ns
toE	OE to Output Delay	CE = VIL		65		75		100		120		150	ns
t <sub>DF(4)</sub>	OE High to Output Float	CE = VIL		55	0	55	0	60	0	105	0	130	ns
tон	Output Hold from Address CE or OE Whichever Occurred First	CE = OE = V <sub>IL</sub>	0		0		0		0		0		ns

# CAPACITANCE<sup>(5)</sup> (T<sub>amb</sub> = 25°C, f = 1 MHz)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
CIN	Input Capacitance	V <sub>IN</sub> = 0V		4	6	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V		8	12	pF

Notes:

 V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>
 V<sub>PP</sub> may be connected directly to V<sub>CC</sub> except during programming
 The supply current would then be the sum of I<sub>CC</sub> and I<sub>PP1</sub>.

 Typical values are for T<sub>amb</sub> = 25°C and nominal supply voltages.

This parameter is only sampled and not 100% tested. Output Float is defined as the point where data is no longer driven-see time discrete. timing diagram.

5. This parameter is only sampled and is not 100% tested.

# **READ OPERATION (Continued)**

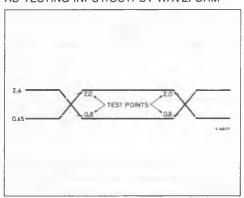
AC TEST CONDITIONS

Output Load: 100pF + 1TTL Gate Input Rise and Fall Times: ≤20ns Input Pulse Levels: 0.45 to 2.4V

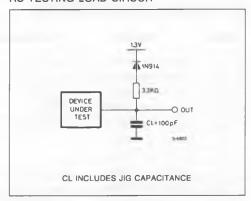
Timing Measurement Reference Levels: Inputs 0.8 and 2V

Outputs 0.8 and 2V

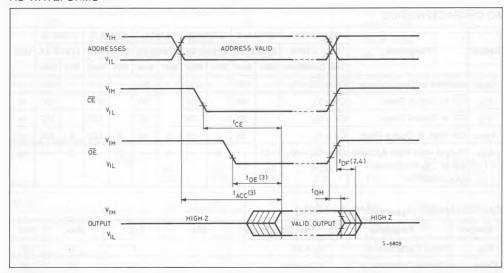
### AC TESTING INPUT/OUTPUT WAVEFORM



# AC TESTING LOAD CIRCUIT



#### AC WAVEFORMS



- 1. Typical values are for Tamb = 25°C and nominal supply voltage.
- 2. This parameter is only sampled and not 100% tested.
- ŌE may be delayed up to t<sub>ACC</sub> t<sub>OE</sub> after the falling edge ŒE without impact on t<sub>ACC</sub>.
   t<sub>DF</sub> is specified from ŌE or ŒE whichever occurs first.

#### **DEVICE OPERATION**

The seven modes of operations of the M2764A are listed in the Operating Modes. A single 5V power supply is required in the read mode. All inputs are  $T\Gamma$ L levels except for  $V_{PP}$  and 12V on A9 for Electronic Signature.

#### READ MODE

The M2764A has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for device selection. Output Enable (OE) is the output control and should be used to gate data to the output pins, independent of device selection.

Assuming that addresses are stable, address access time ( $t_{ACC}$ ) is equal to delay from  $\overline{CE}$  to output ( $t_{CE}$ ). Data is available at the outputs after the falling edge of  $\overline{OE}$ , assuming that  $\overline{CE}$  has been low and addresses have been stable for at least  $t_{ACC}$ - $t_{OE}$ -

## STANDBY MODE

The M2764A has a standby mode which reduces the maximum active power current from 75 mA to 35 mA. The M2764A is placed in the standby mode by applying a TTL high signal to the  $\overline{CE}$  input. When in the standby mode, the outputs are in a high impedance state, independent of the  $\overline{OE}$  input.

#### **OUTPUT OR-TIFING**

Because EPROMs are usually used in larger memory arrays, the product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

a) the lowest possible memory power dissipation
 b) complete assurance that output bus contention
 will not occur.

For the most efficient use of these two control lines, Œ should be decoded and used as the primary device selecting function, while Œ should be made a common connection to all devices in the array and connected to the READ line from the system control bus.

This assures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is desired from a particular memory device.

#### SYSTEM CONSIDERATIONS

The power switching characteristics of NMOS-E3 EPROMs require careful decoupling of the devices. The supply current,  $I_{CC}$ , has three segments that are of interest to the system designer: the standby current level, the active current level, and tran-

sient current peaks that are produced by the falling and rising edges of  $\overline{\text{CE}}$ . The magnitude of this transient current peaks is dependent on the output capacitive and inductive loading of the device. The associated transient voltage peaks can be suppressed by complying with the two line output control and by properly selected decoupling capacitors. It is recommended that a 1  $\mu\text{F}$  ceramic capacitor be used on every device between  $V_{\text{CC}}$  and GND.

This should be a high frequency capacitor of low inherent inductance and should be placed as close to the device as possible. In addition, a 4.7  $\mu F$  bulk electrolytic capacitors should be used between  $V_{CC}$  and GND for every eight devices. The bulk capacitor should be located near where the power supply is connected to the array. The purpose of the bulk capacitor is to overcome the voltage drop caused by the inductive effects of PCB traces.

#### **PROGRAMMING**

Caution: exceeding 14V on pin 1 ( $V_{PP}$ ) will damage the M2764A.

When delivered, and after each erasure, all bits of the M2764A are in the "1" state. Data is introduced by selectively programming "0s" into the desired bit locations. Although only "0s" will be programmed, both "1s" and "0s" can be present in the data word. The only way to change a "0" to a "1" is by ultraviolet light erasure.

The M2764A is in the programming mode when  $V_{PP}$  input is at 12.5V and CE and PGM are at TTL low. The data to be programmed is applied 8 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL.

#### FAST PROGRAMMING ALGORITHM

Fast Programming Algorithm rapidly programs M2764A EPROMs using an efficient and reliable method suited to the production programming environment. Programming reliability is also ensured as the incremental program margin of each byte is continually monitored to determine when it has been successfully programmed. A flowchart of the M2764A Fast Programming Algorithm is shown on the last page. The Fast Programming Algorithm utilizes two different pulse types: initial and overprogram.

The duration of the initial  $\overline{PGM}$  pulse (s) is one millisecond, which will then be followed by a longer overprogram pulse of length 3Xmsec. (X is an iteration counter and is equal to the number of the initial one millisecond pulses applied to a particular M2764A location), before a correct verify occurs. Up to 25 one-millisecond pulses per byte are provided for before the over program pulse is applied.

## **DEVICE OPERATION (Continued)**

The entire sequence of program pulses and byte verifications is performed at  $V_{CC} = 6V$  and  $V_{PP} = 12.5V$ . When the Fast Programming cycle has been completed, all bytes should be compared to the original data with  $V_{CC} = V_{PP} = 5V$ .

#### PROGRAM INHIBIT

Programming of multiple M2764As in parallel with different data is also easily accomplished. Except for CE, all like inputs (including OE) of the parallel M2764A may be common. A TTL low pulse applied to a M2764A's CE input, with V<sub>PP</sub> at 12.5V, will program that M2764A. A high level CE input inhibits the other M2764A from being programmed.

#### PROGRAM VERIFY

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with  $\overline{\text{OE}}$  at  $V_{\text{IL}}$ ,  $\overline{\text{CE}}$  at  $V_{\text{IL}}$ ,  $\overline{\text{PGM}}$  at  $V_{\text{IH}}$  and  $V_{\text{PP}}$  at 12.5V.

#### **ELECTRONIC SIGNATURE**

The Electronic Signature mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25°C ±5°C ambient temperature range that is required when programming the M2764A. To activate this mode, the programming equipment must force 11.5V to 12.5V on address line A9 (pin 24) of the M2764A. Two identifier bytes may than be sequen-

ced from the device outputs by toggling address line A0 (pin 10) from  $V_{\rm IL}$  to  $V_{\rm IH}$ . All other address lines must be held at  $V_{\rm IL}$  during Electronic Signature mode. Byte 0 (A0 =  $V_{\rm IL}$ ) represents the manufacturer code and byte 1 (A0 =  $V_{\rm IH}$ ) the device identifier code. For the SGS-THOMSON M2764A, these two identifier bytes are given below. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (07) defined as the parity bit.

### **ERASURE OPERATION**

The erasure characteristic of the M2764A is such that erasure begins when the cells are exposed to light with wavelengths shorter than approximately 4000 Angstrom A. It should be noted that sunlight and some type of fluorescent lamps have wavelengths in the 3000-4000 A range. Data shows that constant exposure to room level fluorescent lighting could erase a typical M2764A in about 3 years, while it would take approximately 1 week to cause erasure when expose to direct sunlight. If the M2764A is to be exposed to these type of lighting conditions for extended periods of time, it is suggested that opaque labels be put over the M2764A window to prevent unintentional erasure. The recommended erasure procedure for the M2764A is exposure to short wave ultraviolet light which has wavelength 2537 Å. The integrated dose (i.e. UV intensity x exposure time) for erasure should be a minimum of 15 W-sec/cm2. The erasure time with this dosage is approximately 15 to 20 minutes using an ultraviolet lamp with 12000 uW/cm<sup>2</sup> power rating. The M2764A should be placed within 2.5 cm (1 inch) of the lamp tubes during the erasure. Some lamps have a filter on their tubes which should be removed before erasure.

#### **ELECTRONIC SIGNATURE MODE**

PINS	A0 (10)	O7 (19)	O6 (18)	O5 (17)	O4 (16)	O3 (15)	O2 (13)	O1 (12)	O0 (11)	Hex Data
MANUFACTURER CODE	V <sub>IL</sub>	0	0	1	0	0	0	0	0	20
DEVICE CODE	V <sub>IH</sub>	0	0	0	0	1	0	0	0	08

# **PROGRAMMING OPERATION** ( $T_{amb} = 25^{\circ}C \pm 5^{\circ}C$ , $V_{CC}^{(1)} = 6V \pm 0.25V$ , $V_{PP}^{(1)} = 12.5V \pm 0.3V$ )

# DC AND OPERATING CHARACTERISTIC

Cumbal	Parameter	Test Conditions		Values		Unit
Symbol	Parameter	rest conditions	Min.	Тур.	Max.	Unit
ILI	Input Current (All Inputs)	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>			10	μΑ
VIL	Input Low Level (All Inputs)		-0.1		0.8	٧
V <sub>IH</sub>	Input High Level		2.0		Vcc	V
V <sub>OL</sub>	Output Low Voltage During Verify	I <sub>OL</sub> = 2.1 mA			0.45	V
V <sub>OH</sub>	Output High Voltage During Verify	$I_{OH} = -400 \ \mu A$	2.4			V
I <sub>CC2</sub>	V <sub>CC</sub> Supply Current (Program & Verify)				75	mA
I <sub>PP2</sub>	V <sub>PP</sub> Supply Current (Program)	CE = V <sub>IL</sub>			50	mA
V <sub>ID</sub>	A9 Electronic Signature Voltage		11.5		12.5	V

### AC CHARACTERISTICS

Cumbal	Parameter	Test Conditions		Values		
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
tas	Address Setup Time		2			μS
toes	OE Setup Time		2			μS
t <sub>DS</sub>	Data Setup Time		2			μS
t <sub>AH</sub>	Address Hold Time		0			μS
t <sub>DH</sub>	Data Hold Time		2			μS
t <sub>DFP</sub> (4)	Output Enable Output Float Delay		0		130	ns
t <sub>VPS</sub>	V <sub>PP</sub> Setup Time		2			μS
t <sub>VCS</sub>	V <sub>CC</sub> Setup Time		2			μS
tCES	CE Setup Time		2			μS
tpW	PGM Initial Program Pulse Width	(see Note 3)	0.95	1.0	1.05	ms
<sup>‡</sup> OPW	PGM Overprogram Pulse Width	(see Note 2)	2.85		78.75	ms
toE	Data Valid from OE				150	ns

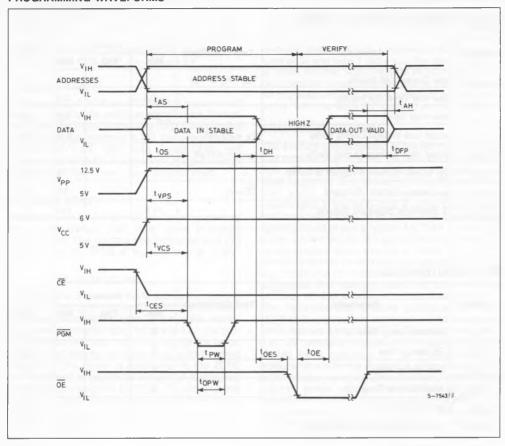
#### Notes:

V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.
 The length of the overprogram pulse may vary from 2.85msec to 78.75msec as a function of the iteration counter value X.
 Initial Program Pulse width tolerance is 1msec ±5%.

4. This parameter is only sampled and not 100% tested

Output Float is defined as the point where data is no longer driven (see timing diagram).

# **PROGRAMMING WAVEFORMS**



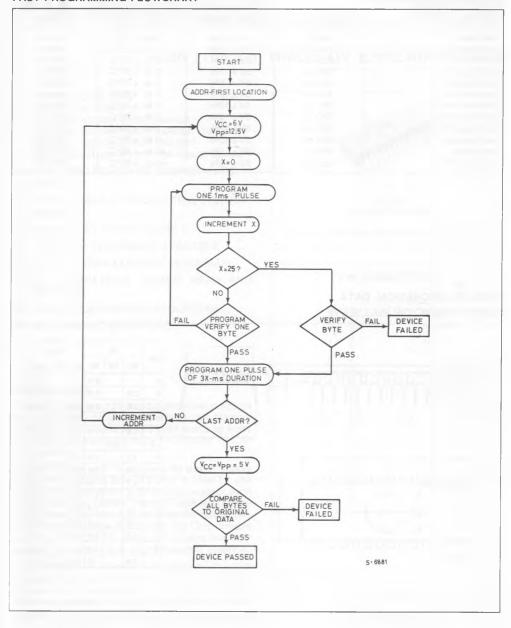
Notes:

1. The input timing reference level is 0.8V for a V<sub>IL</sub> and 2V for a V<sub>IH</sub>.

2. t<sub>OE</sub> and t<sub>DFP</sub> are characteristics of the device but must be accommodated by the programmer.

3. When programming the M2764A a 0.1 µF capacitor is required across V<sub>PP</sub> and GROUND to suppress spurious voltage transients which can damage the device.

# FAST PROGRAMMING FLOWCHART



### ORDERING INFORMATION

Part Number	Access Time	Supply Voltage	Temp. Range	Package
M2764A-1F1	180 ns	5V± 5%	0 to +70°C	DIP-28
M2764A-2F1	200 ns	5V ± 5%	0 to +70°C	DIP-28
M2764AF1	250 ns	5V ± 5%	0 to +70°C	DIP-28
M2764A-3F1	300 ns	5V ± 5%	0 to +70°C	DIP-28
M2764A-4F1	450 ns	5V ± 5%	0 to +70°C	DIP-28
M2764A-18F1	180 ns	5V ± 10%	0 to +70°C	DIP-28
M2764A-20F1	200 ns	5V ± 10%	0 to +70°C	DIP-28
M2764A-25F1	250 ns	5V ± 10%	0 to +70°C	DIP-28
M2764A-30F1	300 ns	5V ± 10%	0 to +70°C	DIP-28
M2764A-45F1	450 ns	5V ± 10%	0 to +70°C	DIP-28
M2764AF6	250 ns	5V ± 5%	-40 to +85°C	DIP-28
M2764A-4F6	450 ns	5V ± 5%	- 40 to +85°C	DIP-28

# PACKAGE MECHANICAL DATA

28-PIN CERAMIC DIP BULL'S EYE

